

Title (en)
METHOD OF INTEGRALLY BONDING A RADIATION SHIELDING AND THERMALLY CONDUCTIVE GASKET TO A SURFACE AND ARTICLE
FABRICATED BY SAME.

Title (de)
VERFAHREN ZUM INTEGRIERTEN VERSCHWEISSEN EINES STRAHLUNGSABSCHIRMENDEN UND WÄRMELEITENDEN
ABDICHTUNGSSTÜCKS AN EINE OBERFLÄCHE UND SO ERZEUGTER GEGENSTAND.

Title (fr)
PROCEDE DE SOUDAGE INTEGRAL D'UN JOINT D'ETANCHEITE THERMOCONDUCTEUR ANTI-RADIATION SUR UNE SURFACE ET
ARTICLE OBTENU GRACE A CE PROCEDE.

Publication
EP 0135533 A4 19860512 (EN)

Application
EP 84900778 A 19840104

Priority
US 45566283 A 19830105

Abstract (en)
[origin: WO8402680A1] The invention pertains to radiation-shielding gaskets. Gaskets which are bonded to surfaces by separate adhesive layers permit electromagnetic radiation to pass between the gasket and the surface. The invention uses a bonding agent within the gasket material which permits the gasket to be directly bonded to the surface. A method of making the shielding gasket integral with a surface comprises the steps of (a) preparing a gasket material consisting of a mixture of an elastomer, a conductive filler, a catalyst and a bonding agent; (b) filling a mold with the gasket material; (c) covering the mold with a surface chosen to be bonded to the gasket; and (d) curing the gasket material in contact with the surface to utilize the bonding agent to bond the gasket material to the chosen surface. The article fabricated by this method comprises a gasket (18b), consisting of a mixture of an elastomer (26), a conductive filler (30) and a bonding agent (28), bonded to a surface (38) by the bonding agent during curing and having the particles comprising the conductive filler held in physical contact with the surface and with one another by the elastomer to which the particles are bonded.

IPC 1-7
; **H01B 1/20**; **H05K 9/00**

IPC 8 full level
B29C 65/48 (2006.01); **B29C 65/36** (2006.01); **B29C 70/74** (2006.01); **B29C 70/78** (2006.01); **B29C 70/88** (2006.01); **H01B 1/20** (2006.01); **H01B 1/22** (2006.01); **H01B 1/24** (2006.01); **H05K 9/00** (2006.01); **B29L 31/26** (2006.01)

CPC (source: EP US)
B29C 70/74 (2013.01 - EP US); **B29C 70/78** (2013.01 - EP US); **B29C 70/882** (2013.01 - EP US); **H01B 1/22** (2013.01 - EP US); **H01B 1/24** (2013.01 - EP US); **H05K 9/0015** (2013.01 - EP US); **B29K 2021/00** (2013.01 - EP US); **B29K 2083/00** (2013.01 - EP US); **B29K 2105/16** (2013.01 - EP US); **B29K 2995/0005** (2013.01 - EP US); **B29L 2031/265** (2013.01 - EP US); **Y10S 277/92** (2013.01 - EP US); **Y10S 277/936** (2013.01 - EP US); **Y10S 277/941** (2013.01 - EP US); **Y10S 277/944** (2013.01 - EP US)

Citation (search report)
• [X] FR 2484688 A1 19811218 - FRANCE ETAT [FR]
• [X] US 3888815 A 19750610 - BESSMER STANLEY J, et al
• [YP] WESCON TECHNICAL PAPERS, vol. 27, session record 9, art. 4, November 1983, pages 1-4, San Francisco, US; J.W. WRIGHT: "Material selection for good EMI/RFI gasket design"

Designated contracting state (EPC)
AT BE CH DE FR GB LI LU NL SE

DOCDB simple family (publication)
WO 8402680 A1 19840719; CA 1219328 A 19870317; EP 0135533 A1 19850403; EP 0135533 A4 19860512; JP S60500393 A 19850322; US 4575578 A 19860311

DOCDB simple family (application)
US 8400029 W 19840104; CA 444402 A 19831229; EP 84900778 A 19840104; JP 50080084 A 19840104; US 45566283 A 19830105